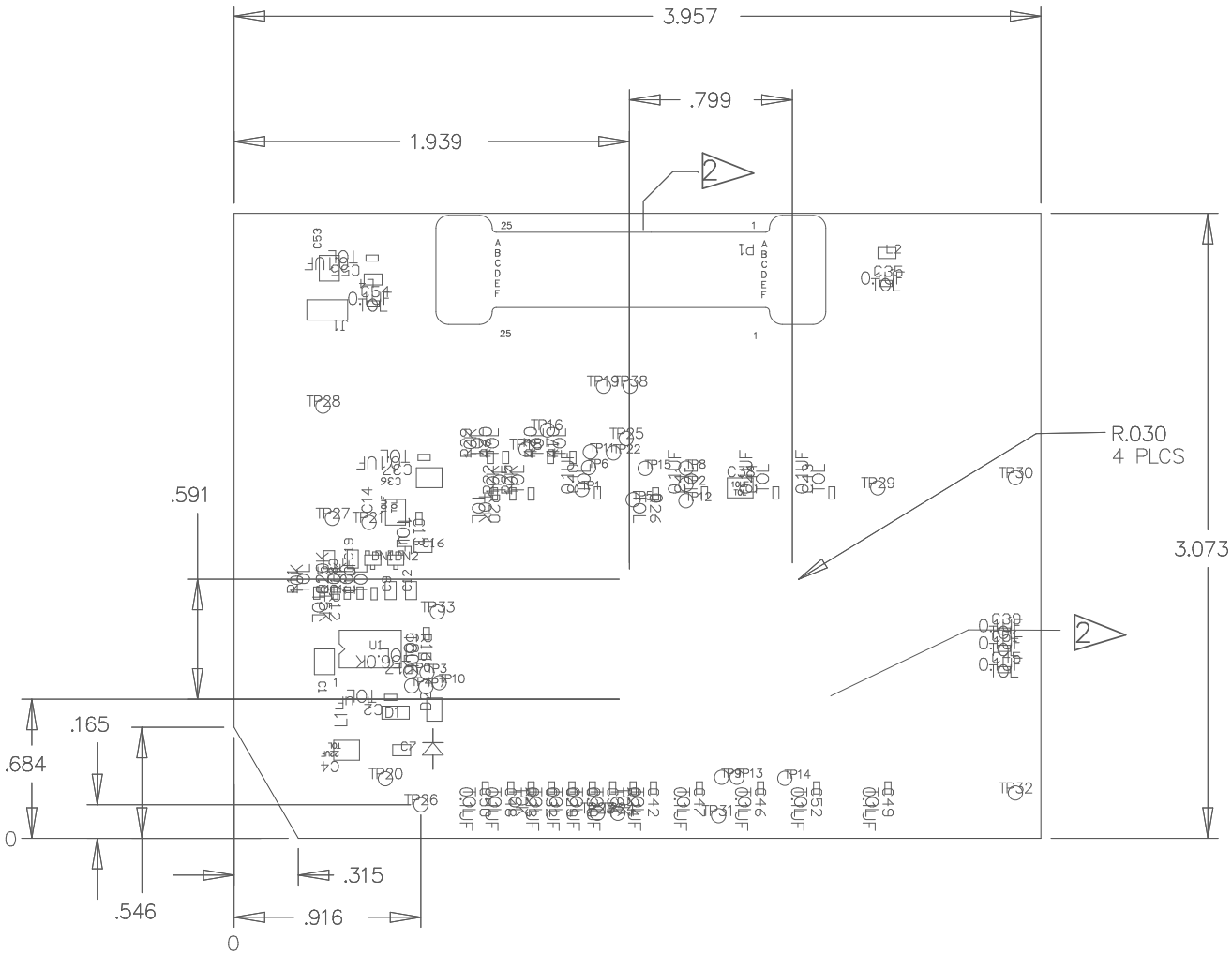
+/−.002



PRIMARY SIDE VIEW

FABRICATION DRAWING

15

FAB NOTES:

1. ALL DIMENSIONS ARE IN INCHES, UNLESS OTHERWISE NOTED.

2. THE PWB SHALL BE FABRICATED TO IPC−6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC−A−600, CLASS 2. CURRENT REVISIONS.

3. BOARD MATERIAL SHALL BE 180 Tg/340 Td ISOLA FR−370HR OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC−4101B. COLOR: NATURAL.

4. BOARD MATERIAL & CONSTRUCTION TO BE U.L. APPROVED AND MARKED ON THE FINISHED BOARD.

5. MINIMUM COPPER WALL THICKNESS OF PLATED−THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .002 INCH.

6. OVERALL BOARD THICKNESS TO BE .062 +/− 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.

7. MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.

8. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC−D−356 NETLIST.

PROCESS NOTES:

1. EXCEPT AS NOTED IN NOTE 2, PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, NICKEL 100 MICROINCHES THK GOLD 2−6 MICROINCHES THK MIN.

2. PLATE INDICATED AREAS OF U2 AND P1(BOTH SIDES) WITH ELECTROLYTIC PLATING 100−200 MICRO−INCHES OF NICKEL UNDER 35−50 MICRO−INCHES OF GOLD.

3. APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC), COLOR: GREEN. SOLDERMASK SHALL CONFORM TO IPC−SM−840, CLASS H. CURRENT REV.

4. SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS. FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS.

5. APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.

STACK−UP	MINIMUM FINAL COPPER WEIGHT
LAYER 1 PRIMARY SIDE	1.5 OZ Cu
LAYER 2 GND PLANE	1 OZ Cu
LAYER 3 SIGNAL	.5 OZ Cu
LAYER 4 GND PLANE	1 OZ Cu
LAYER 5 POWER PLANE	1 OZ Cu
LAYER 6 SIGNAL	.5 OZ Cu
LAYER 7 GND PLANE	1 OZ Cu
LAYER 8 SECONDARY SIDE	1.5 OZ Cu

IMPEDANCE TOLERANCE =+/− 10%

ADJUST DIELECTRIC THICKNESS TO MEET SPECIFIED IMPEDANCE.

ASY1